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ESI Launches Newest Addition to Laser Micromachining Portfolio

New Garnet™ Platform Expands Portfolio to Deliver Precision, Accuracy and Throughput for Larger Format Manufacturing in China

SHANGHAI, China, Feb. 16, 2016 (GLOBE NEWSWIRE) -- Electro Scientific Industries, Inc. (NASDAQ:ESIO), an innovator of laser-based manufacturing solutions for the micromachining industry, today introduced the Garnet™ adaptable laser micromachining platform for high-volume cutting, marking, drilling or engraving applications. Garnet™ complements ESI's current micromachining portfolio delivering lower cost of ownership specifically for China manufacturers' need for larger format materials. The Garnet™ platform's 300x300mm stage allows manufacturers working with large-format materials to optimize production and service for a wider range of customer needs.

The Garnet™ platform is positioned between the Lumen™ platform, ideal for high-end prototyping and production applications where precision and flexibility are paramount, and the lower-cost Jade™ platform, introduced earlier this year for less demanding general purpose laser machining applications.

The Garnet™ platform drives down total cost of ownership by combining ESI's engineering expertise with China's manufacturing cost advantages. To meet the market's wide range of application needs, Garnet™ is built on a versatile base frame capable of multiple laser engine and optics combinations. The Garnet™ platform can be configured and delivered rapidly to meet the short product ramp times of contract manufacturers in China.

"Manufacturers of larger format components in consumer electronics, automotive and soft goods markets have the same range of application needs and pressures to lower their cost of ownership as those manufacturing smaller components in the consumer electronics market," said Mantreh Nournia, General Manager, Micro Machining Division, ESI. "To meet these market needs and increase manufacturer's capabilities on large-format materials, we launched the Garnet™ platform as the third system in our micromachining series and ESI's second system built on a low-cost China platform. Garnet™ extends our expertise with the Jade™ and Lumen™ platforms to address a broad set of laser material interaction applications at a very attractive cost of ownership."

The Garnet™ platform includes many capabilities found in high-end prototyping tools including superior configuration flexibility, compound beam motion control and the highest levels of precision in the industry for this class of product. Garnet™ lowers overall cost of ownership with a 25 percent jump in placement accuracy compared to other mid-range laser systems.

Availability and Demonstrations

The Garnet™ platform is available now for purchase in China. It is available for demonstration by appointment at ESI's Shanghai Center for Advanced Development. Contact ESI China Sales at +86.21.3392.7070

About ESI

ESI's integrated solutions allow industrial designers and process engineers to control the power of laser light to transform materials in ways that differentiate their consumer electronics, wearable devices, semiconductor circuits and high-precision components for market advantage. ESI's laser-based manufacturing solutions feature the micro-machining industry's highest precision and speed, and target the lowest total cost of ownership. ESI is headquartered in Portland, Ore., with global operations from the Pacific Northwest to the Pacific Rim. More information is available at www.esi.com.

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